

Amplifier Transistor PNP Silicon

2N5087

ON Semiconductor Preferred Device

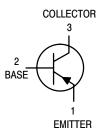
MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector–Emitter Voltage	VCEO	50	Vdc
Collector-Base Voltage	V _{CBO}	50	Vdc
Emitter–Base Voltage	V _{EBO}	3.0	Vdc
Collector Current — Continuous	IC	50	mAdc
Total Device Dissipation @ T _A = 25°C Derate above 25°C	PD	625 5.0	mW mW/°C
Total Device Dissipation @ T _C = 25°C Derate above 25°C	PD	1.5 12	Watts mW/°C
Operating and Storage Junction Temperature Range	T _J , T _{Stg}	-55 to +150	°C



THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	200	°C/W
Thermal Resistance, Junction to Case	$R_{\theta JC}$	83.3	°C/W



ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic		Min	Max	Unit
OFF CHARACTERISTICS				
Collector–Emitter Breakdown Voltage ⁽¹⁾ (IC = 1.0 mAdc, I _B = 0)	V(BR)CEO	50	_	Vdc
Collector–Base Breakdown Voltage (I _C = 100 μAdc, I _E = 0)	V(BR)CBO	50	_	Vdc
Collector Cutoff Current (V _{CB} = 35 Vdc, I _E = 0)	I _{CBO}	_	50	nAdc
Emitter Cutoff Current (VEB = 3.0 Vdc, I _C = 0)	I _{EBO}	_	50	nAdc

^{1.} Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2.0%.

Preferred devices are ON Semiconductor recommended choices for future use and best overall value.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted) (Continued)

Characteristic	Symbol	Min	Max	Unit
ON CHARACTERISTICS			l	
DC Current Gain (IC = 100 μ Adc, VCE = 5.0 Vdc) (IC = 1.0 mAdc, VCE = 5.0 Vdc) (IC = 10 mAdc, VCE = 5.0 Vdc)(1)	hFE	250 250 250	800 — —	_
Collector–Emitter Saturation Voltage (I _C = 10 mAdc, I _B = 1.0 mAdc)	VCE(sat)	_	0.3	Vdc
Base–Emitter On Voltage (I _C = 1.0 mAdc, V _{CE} = 5.0 Vdc)	VBE(on)	_	0.85	Vdc
SMALL-SIGNAL CHARACTERISTICS				
Current–Gain — Bandwidth Product (I _C = 500 μAdc, V _{CE} = 5.0 Vdc, f = 20 MHz)	fT	40	_	MHz
Collector–Base Capacitance (V _{CB} = 5.0 Vdc, I _E = 0, f = 1.0 MHz)	C _{cb}	_	4.0	pF
Small–Signal Current Gain (I _C = 1.0 mAdc, V _{CE} = 5.0 Vdc, f = 1.0 kHz)	h _{fe}	250	900	_
Noise Figure (IC = 20 μ Adc, VCE = 5.0 Vdc, RS = 1.0 k Ω , f = 1.0 kHz) (IC = 100 μ Adc, VCE = 5.0 Vdc, RS = 3.0 k Ω , f = 1.0 kHz)	NF	_	2.0 2.0	dB

^{1.} Pulse Test: Pulse Width $\leq 300~\mu s,$ Duty Cycle $\leq 2.0\%.$

TYPICAL NOISE CHARACTERISTICS

 $(V_{CE} = -5.0 \text{ Vdc}, T_{A} = 25^{\circ}\text{C})$

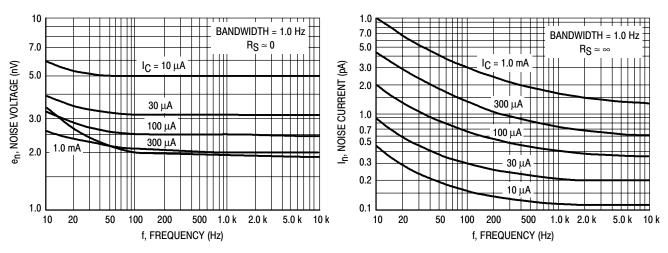


Figure 1. Noise Voltage

Figure 2. Noise Current

NOISE FIGURE CONTOURS

 $(VCE = -5.0 \text{ Vdc}, T_A = 25^{\circ}C)$

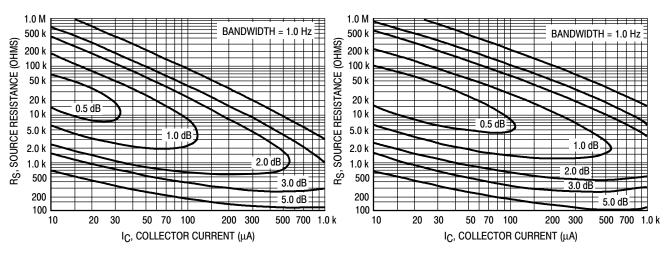


Figure 3. Narrow Band, 100 Hz

Figure 4. Narrow Band, 1.0 kHz

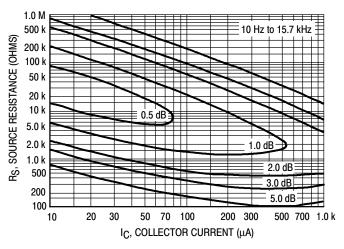


Figure 5. Wideband

Noise Figure is Defined as:

$$NF = 20 \log_{10} \left[\frac{e_n^2 + 4KTR_S + I_n^2 R_S^2}{4KTR_S} \right]^{1/2}$$

en = Noise Voltage of the Transistor referred to the input. (Figure 3)

In = Noise Current of the Transistor referred to the input. (Figure 4)

 $K = Boltzman's Constant (1.38 x 10^{-23} j/{}^{\circ}K)$

T = Temperature of the Source Resistance (°K)

Rs = Source Resistance (Ohms)

TYPICAL STATIC CHARACTERISTICS

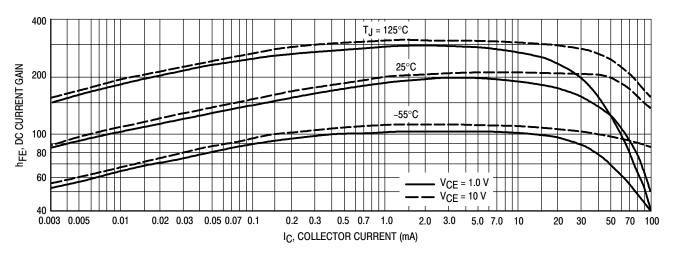


Figure 6. DC Current Gain

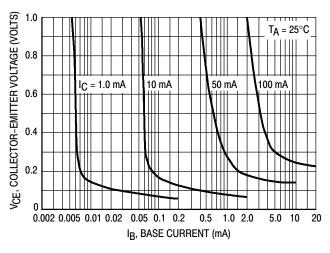


Figure 7. Collector Saturation Region

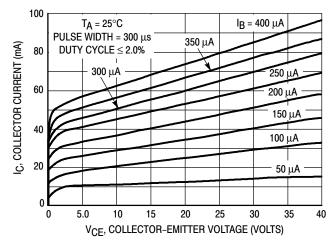


Figure 8. Collector Characteristics

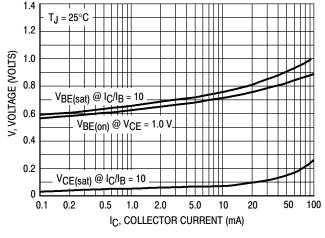


Figure 9. "On" Voltages

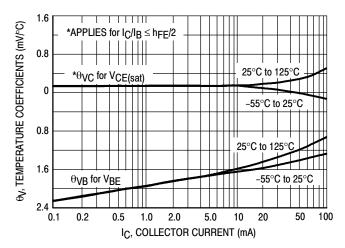
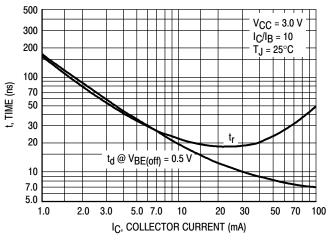


Figure 10. Temperature Coefficients

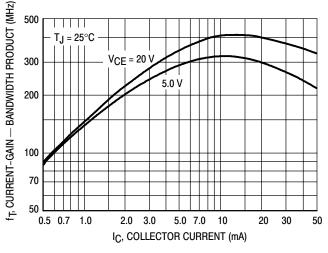
TYPICAL DYNAMIC CHARACTERISTICS



1000 $V_{CC} = -3.0 \text{ V}$ 700 $I_C/I_B = 10$ 500 $I_{B1} = I_{B2}$ T_J = 25°C 300 200 t, TIME (ns) 100 70 50 30 20 10 -1.0 -5.0 -7.0 -10 -20 -50 -70 -100 IC, COLLECTOR CURRENT (mA)

Figure 11. Turn-On Time

Figure 12. Turn-Off Time



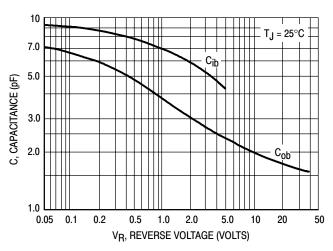
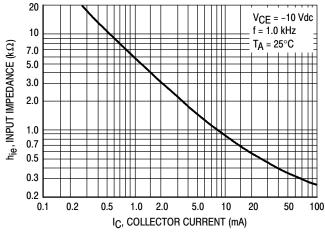


Figure 13. Current-Gain — Bandwidth Product

Figure 14. Capacitance



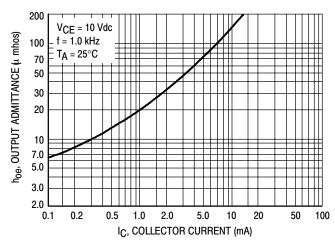


Figure 15. Input Impedance

Figure 16. Output Admittance

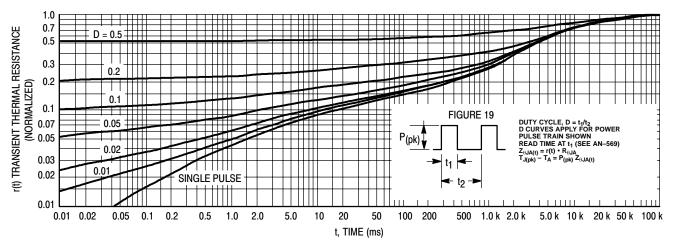


Figure 17. Thermal Response

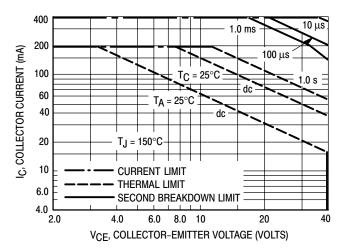


Figure 18. Active-Region Safe Operating Area

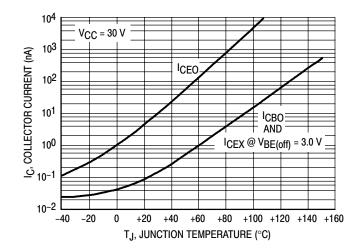


Figure 19. Typical Collector Leakage Current

The safe operating area curves indicate I_C–V_{CE} limits of the transistor that must be observed for reliable operation. Collector load lines for specific circuits must fall below the limits indicated by the applicable curve.

The data of Figure 18 is based upon $T_{J(pk)} = 150^{\circ}C$; T_{C} or T_{A} is variable depending upon conditions. Pulse curves are valid for duty cycles to 10% provided $T_{J(pk)} \le 150^{\circ}C$. $T_{J(pk)}$ may be calculated from the data in Figure 17. At high case or ambient temperatures, thermal limitations will reduce the power than can be handled to values less than the limitations imposed by second breakdown.

DESIGN NOTE: USE OF THERMAL RESPONSE DATA

A train of periodical power pulses can be represented by the model as shown in Figure 19. Using the model and the device thermal response the normalized effective transient thermal resistance of Figure 17 was calculated for various duty cycles.

To find $Z_{\theta JA(t)}$, multiply the value obtained from Figure 17 by the steady state value $R_{\theta JA}$.

Example

The 2N5087 is dissipating 2.0 watts peak under the following conditions:

$$t_1 = 1.0 \text{ ms}, t_2 = 5.0 \text{ ms} (D = 0.2)$$

Using Figure 17 at a pulse width of 1.0 ms and D = 0.2, the reading of r(t) is 0.22.

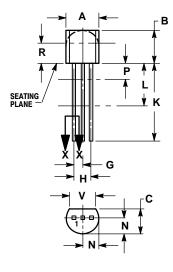
The peak rise in junction temperature is therefore

 $\Delta T = r(t) \times P_{(pk)} \times R_{\theta JA} = 0.22 \times 2.0 \times 200 = 88^{\circ}C.$

For more information, see ON Semiconductor Application Note AN569/D, available from the Literature Distribution Center or on our website at www.onsemi.com.

PACKAGE DIMENSIONS

TO-92 (TO-226) CASE 29-11 ISSUE AL





STYLE 1:
PIN 1. EMITTER
2. BASE
3. COLLECTOR

- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: INCH.

 3. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.

 4. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.175	0.205	4.45	5.20
В	0.170	0.210	4.32	5.33
С	0.125	0.165	3.18	4.19
D	0.016	0.021	0.407	0.533
G	0.045	0.055	1.15	1.39
Н	0.095	0.105	2.42	2.66
J	0.015	0.020	0.39	0.50
K	0.500		12.70	
L	0.250		6.35	
N	0.080	0.105	2.04	2.66
P		0.100		2.54
R	0.115		2.93	
V	0.135		3.43	

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